

**Product / Package Information**

Package	PDIP
Body Size	300 mils
Lead Count	28
Terminal Finish	100Sn

**Environmental Compliance Information**

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.19 E+00	86.0	860000	57.71	577056
Thermosets	Epoxy Resin	Proprietary	1.04 E-01	7.5	75000	5.03	50325
Thermosets	Phenol Resin	Proprietary	5.52 E-02	4.0	40000	2.68	26840
Thermosets	Epoxy Cresol Novolac	29690-82-2	2.76 E-02	2.0	20000	1.34	13420
Other inorganic materials	Carbon Black	1333-86-3	6.90 E-03	0.5	5000	0.34	3355
Subtotal			1.38 E+00	100	1000000	67.10	670895

**Leadframe**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.00 E-01	97.50	975000	29.19	291889
Copper & its alloys	Iron	7439-89-6	1.45 E-02	2.35	23500	0.70	7035
Copper & its alloys	Zinc	7440-66-6	7.39 E-04	0.12	1200	0.04	359
Copper & its alloys	Phosphorus	7723-14-0	1.85 E-04	0.03	300	0.01	90
Subtotal			6.16 E-01	100.00	1000000	29.94	299352

**Internal Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.85 E-03	100.0	1000000	0.09	899

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.21 E-02	100.0	1000000	1.56	15592

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.38 E-03	99.99	1000000	0.07	671

**Chip**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.10 E-02	100.0	1000000	1.02	10229

**Die Attach**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.53 E-03	80	800000	0.17	1715
Thermosets	Epoxy Resin	Proprietary	6.62 E-04	15	150000	0.03	322
Others	Curing agent & hardener	Proprietary	2.21 E-04	5	50000	0.01	107
Subtotal			4.41 E-03	100	1000000	0.21	2144

**Die Coat**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	1.45 E-04	60.4	604000	0.01	70
Other organic materials	Dimethylvinylated & Trimethylated silice	68989-89-6	6.72 E-05	28.0	280000	0.00	33
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	2.40 E-05	10.0	100000	0.00	12
Other organic materials	Ethylbenzene	100-41-4	2.40 E-06	1.0	10000	0.00	1
Other organic materials	Xylene	1330-20-7	1.44 E-06	0.6	6000	0.00	0
Subtotal			2.40 E-04	100	1000000	0.01	117

Package Totals			Weight (g)	Percentage (%)	PPM
			2.06 E+00	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability any inaccuracy of such information.



ADI Proprietary

**Product / Package Information**

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Body Size	300 mils
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Terminal Finish	85Sn15Pb

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High Temperature Compliant	No
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

**Materials Declaration**

**Molding Compound**

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Other inorganic materials	Silica	60676-86-0	1.19 E+00	86.0	860000	57.71	577056
Thermosets	Epoxy Resin	Proprietary	1.04 E-01	7.5	75000	5.03	50325
Thermosets	Phenol Resin	Proprietary	5.52 E-02	4.0	40000	2.68	26840
Thermosets	Epoxy Cresol Novolac	29690-82-2	2.76 E-02	2.0	20000	1.34	13420
Other inorganic materials	Carbon Black	1333-86-3	6.90 E-03	0.5	5000	0.34	3355
Subtotal			1.38 E+00	100	1000000	67.10	670995

**Leadframe**

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Precious metals	Silver	7440-22-4	1.85 E-03	100.0	1000000	0.09	899

**External Leadframe Plating**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.73 E-02	85.0	850000	1.33	13253
Tin & its alloys	Lead	7439-92-1	4.91 E-03	15.0	150000	0.23	2339
Subtotal			3.21 E-02	100.0	1000000	1.56	15592

**Bond Wires**

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.38 E-03	99.99	1000000	0.07	671

**Chip**

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**Die Attach**

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Other organic materials	Dimethyl, Methylhydrogen siloxan	68037-59-2	2.40 E-05	10.0	100000	0.00	12
Other organic materials	Ethylbenzene	100-41-4	2.40 E-06	1.0	10000	0.00	1
Other organic materials	Xylene	1330-20-7	1.44 E-06	0.6	6000	0.00	1
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